

2SK1647(L), 2SK1647(S)

Silicon N Channel MOS FET

REJ03G0963-0200

(Previous: ADE-208-1306)

Rev.2.00

Sep 07, 2005

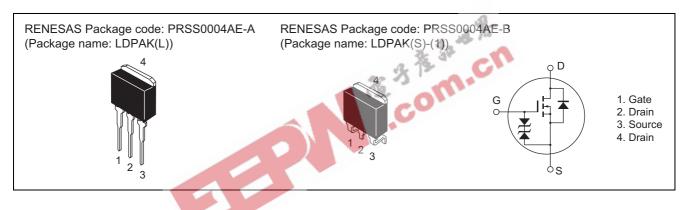
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- · Low drive current
- No secondary breakdown
- Suitable for switching regulator and DC-DC converter

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	900	V
Gate to source voltage	V _{GSS}	±30	V
Drain current	I _D	2	А
Drain peak current	I _{D(pulse)} *1	6	A
Body to drain diode reverse drain current	I _{DR}	2	А
Channel dissipation	Pch ^{*2}	50	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. Value at $T_C = 25$ °C

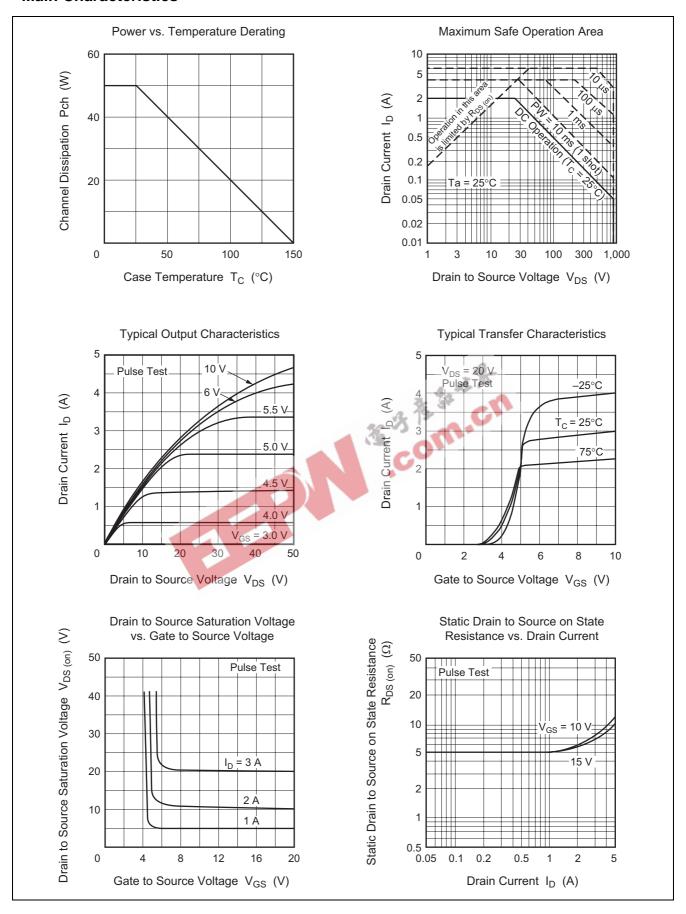
Electrical Characteristics

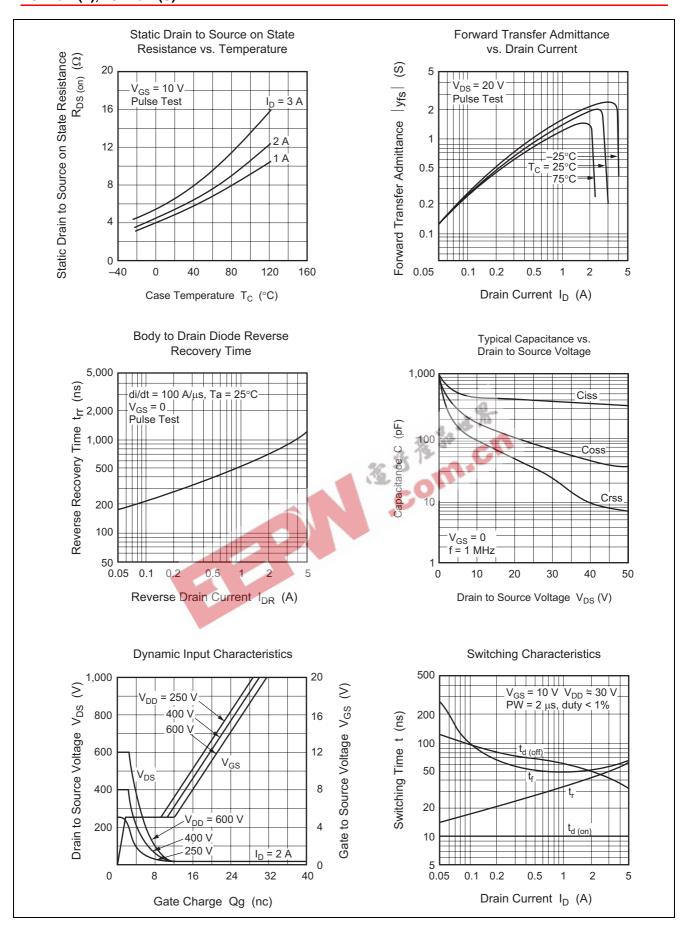
 $(Ta = 25^{\circ}C)$

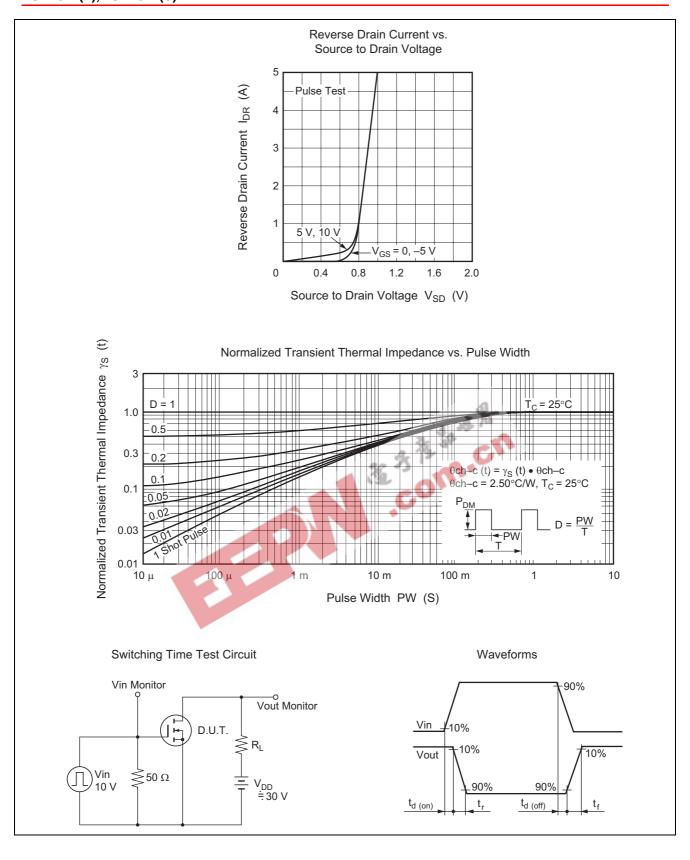
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS} \\$	900		_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±30	1		V	$I_G = \pm 100 \; \mu, \; V_{DS} = 0$
Gate to source leak current	I_{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	1	1	250	μΑ	$V_{DS} = 720 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	2.0	_	3.0	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static drain to source on state resistance	$R_{DS(on)}$	_	5.0	7.0	Ω	$I_D = 1 \text{ A}, V_{GS} = 10 \text{ V}^{*3}$
Forward transfer admittance	y _{fs}	0.9	1.5	~ 0 /	S	$I_D = 1 \text{ A}, V_{DS} = 20 \text{ V}^{*3}$
Input capacitance	Ciss	A-1	425	<u></u>	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss	# 1	17 5	_	pF	f = 1 MHz
Reverse transfer capacitance	Crss	7	85	_	pF	
Turn-on delay time	t _{d(on)}		10	_	ns	$I_D = 1 \text{ A}, V_{GS} = 10 \text{ V},$
Rise time	t _r	_	35	_	ns	$R_L = 30 \Omega$
Turn-off delay time	t _{d(off)}	_	60	_	ns	
Fall time	t _f	_	50	_	ns	
Body to drain diode forward voltage	V _{DF}	_	0.9	_	V	$I_F = 2 A, V_{GS} = 0$
Body to drain diode reverse recovery time	t _{rr}	_	700	_	ns	$I_F = 2 \text{ A}, V_{GS} = 0,$ $di_F/dt = 100 \text{ A}/\mu\text{s}$

Note: 3. Pulse test

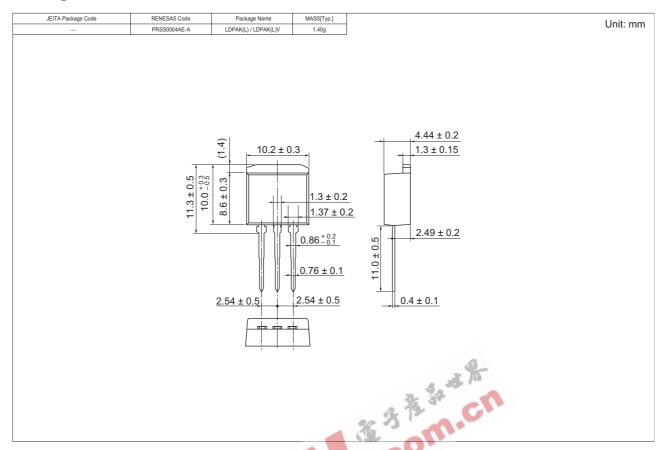
Main Characteristics

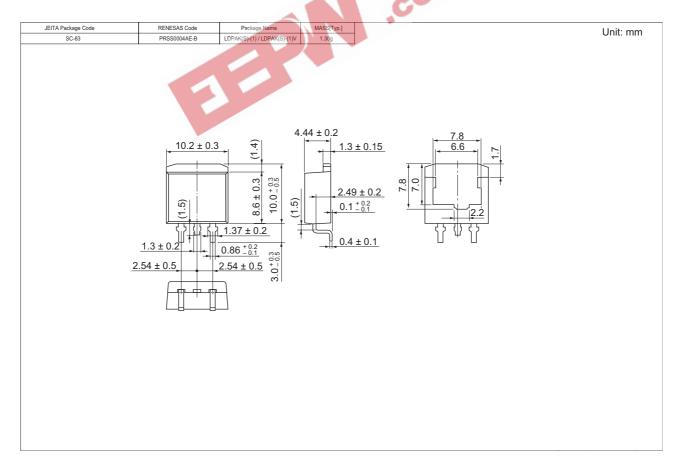






Package Dimensions





Ordering Information

Part Name	Quantity	Shipping Container
2SK1647L-E	500 pcs	Box (Sack)
2SK1647STL-E	1000 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.



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